## TSMC Certifies ANSYS Power Integrity And Electromigration Solutions For 16nm FinFET Technology

## April 15, 2014

PITTSBURGH, April 15, 2014 /PRNewswire/ -- ANSYS, Inc. (NASDAQ: ANSS) announced today that its RedHawk<sup>™</sup> and Totem<sup>™</sup> products are certified for production version 1.0 of Design Rule Manual (DRM) and SPICE model tool certification for TSMC 16-nanometer (nm) FinFET technology. TSMC has certified these solutions for static and dynamic voltage drop analysis and signal and power electromigration (EM) verification.



FinFET technology is a three-dimensional transistor architecture that results in higher-performing and lower power chips used in mobile and high-performance computing applications. Complex metal geometry and high drive currents in FinFET devices make solutions for power integrity and electromigration key requirements. Innovative algorithms within ANSYS technology deliver needed accuracy and reduce turnaround time to meet the increased computational requirements caused by the growing complexity and provide advanced EM verification and accurate IR voltage drop analysis from early in the design flow through sign-off.

"The certification of RedHawk and Totem for 16nm FinFET technology demonstrates how our products are delivering the accuracy required for IR/EM sign-off," said Norman Chang, vice president and senior product strategist of Apache Design, a subsidiary of ANSYS. "By collaborating with TSMC, we are able to provide optimized tools and methodologies for the industry's most advanced process nodes and emerging design technologies."

"A close collaboration between TSMC and Apache on 16nm FinFET Tool Certification enables chip designers to efficiently deliver more robust and reliable systems-on-chips for the next generation electronic products," said Suk Lee, TSMC senior director, Design Infrastructure Marketing Division.

The ANSYS portfolio of product offerings will be showcased at the upcoming <u>TSMC Symposium</u> in San Jose, Austin and Boston and <u>Design</u> Automation Conference (DAC) in exhibit booth #1413.

## About ANSYS, Inc.

ANSYS brings clarity and insight to customers' most complex design challenges through fast, accurate and reliable engineering simulation. Our technology enables organizations — no matter their industry — to predict with confidence that their products will thrive in the real world. Customers trust our software to help ensure product integrity and drive business success through innovation. Founded in 1970, ANSYS employs more than 2,600 professionals, many of them expert in engineering fields such as finite element analysis, computational fluid dynamics, electronics and electromagnetics, and design optimization. Headquartered south of Pittsburgh, U.S.A., ANSYS has more than 75 strategic sales locations throughout the world with a network of channel partners in 40+ countries. Visit www.ansys.com for more information.

ANSYS also has a strong presence on the major social channels. To join the simulation conversation, please visit: www.ansvs.com/Social@ANSYS

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